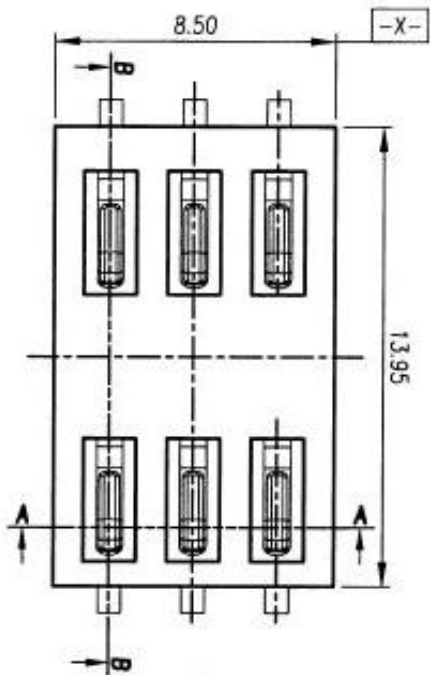
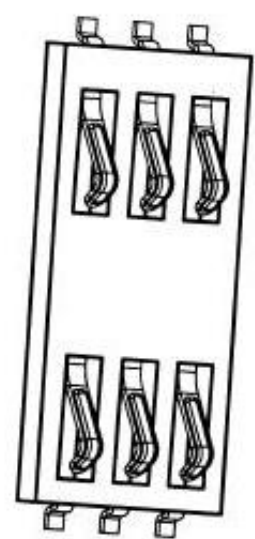
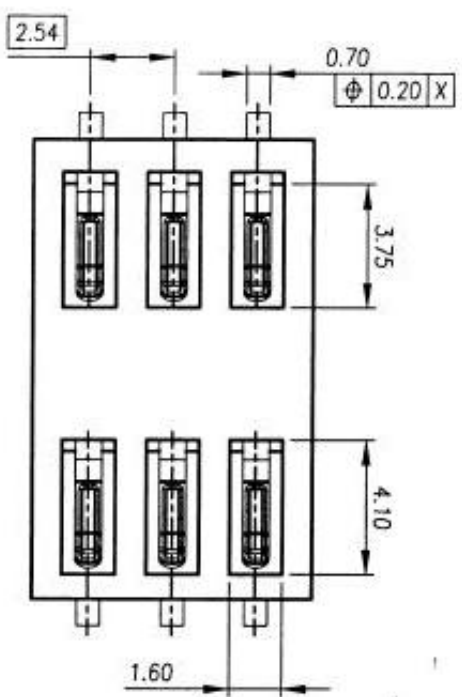


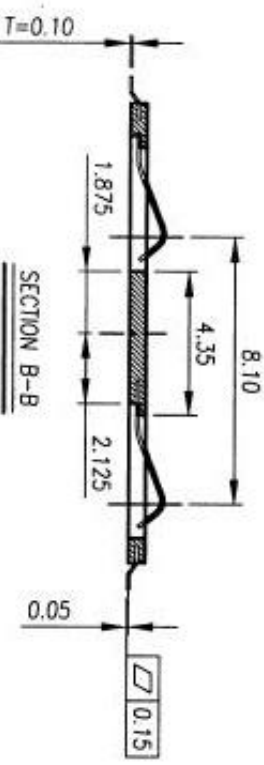
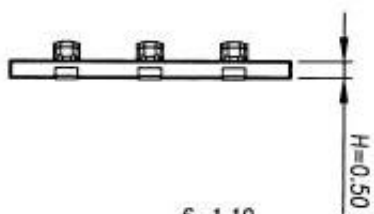
REV	MODIFICATION	DATE	DRAW
B	EN-04-0419	04.14.04*	Aaron
C	EN-04-0505	05.12.04*	Aaron
D	EN-04-0717	07.16.04*	Aaron

NOTES:

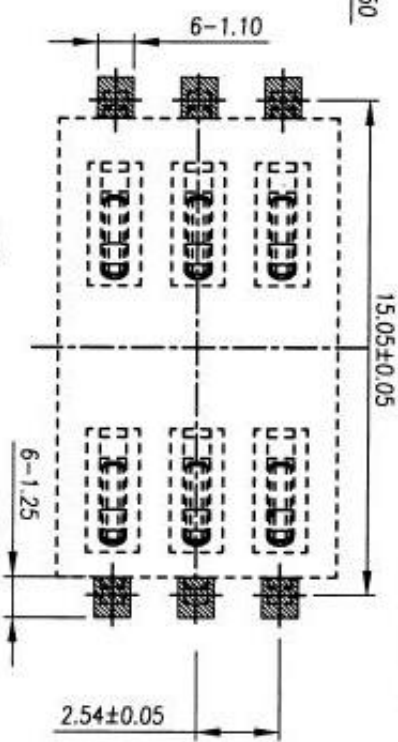
- 1) Material :
Housing : Thermoplastic UL94V-0
Contact : BERYLLIUM C17200R-H,T=0.10mm.
- 2) Plating :
Contact Plating - Gold over 45u" MIN.Nickel
Solder Tail Plating - Gold Flash over 45u" MIN.Nickel
- 3) Contact Forces :
Max. 0.5 N For 0.5mm Contact Deflection.
Min. 0.25 N For 0.5mm Contact Deflection.
- 4) Order Information :
SIMMP-006XXBXX1



SECTION A-A



P.C.B. LAYOUT (TOP VIEW)



30 : GOLD PLATING 30u"
0 : TAPE REEL
1 : TUBE
0 : TIN/LEAD PLATING
1 : LEAD FREE

DIMENSION IN mm [inch]		PROJ. SPEC.	PROJ. SPEC.
TOLERANCE UNLESS OTHERWISE SPECIFIED		PPG SPEC.	PPG SPEC.
.XX±0.30	X: ± 1"	PPP-SIM-005	PPP-SIM-005
.XX±0.20	X: ± 0.5"	CHECK	CHECK
.XXX±0.10	.XX: ± 0.25"	DRAW	DRAW
TITLE		CUSTOMER DRAWING	
Subscriber Identify Module Card		DWG NO. SIMMP-006XXBXX1	
Simple Style Conn. 6 Pin		SHEET 1	
Some Direction Type 0.50mm		REV D	
FILE NO. KFP-052		SCALE 4:1	
SIZE A4		PROJ. SHEET 1	